

wherein the second flexible substrate is formed of the same material as the first flexible substrate.

8. (Amended) The semiconductor device as defined in claim 3,
wherein the electrodes of the semiconductor chip are electrically connected to the wiring pattern by electrically conductive particles dispersed in the resin.

9. (Amended) The semiconductor device as defined in claim 3,
wherein the resin is provided on a surface of the first flexible substrate on which the wiring pattern is formed, and is in close contact with a surface of the wiring pattern facing the second flexible substrate and edge surfaces of the wiring pattern.

29. (Amended) A semiconductor device comprising:
a semiconductor chip on which a plurality of electrodes are formed;
a first flexible substrate in a tape form on which a wiring pattern is formed and on which the semiconductor chip is mounted;
a plurality of external terminals electrically connected to the electrodes with the wiring pattern interposed; and
a second flexible substrate in a tape form adhered to the first flexible substrate by a resin avoiding the semiconductor chip,
wherein the second flexible substrate is formed of a material having a coefficient of thermal expansion substantially equal to a coefficient of thermal expansion of a material of the first flexible substrate.

REMARKS

Claims 1-31 are pending. Claims 12-26 have previously been withdrawn from consideration. By this Amendment claims 1, 8, 9 and 29 are amended.

The attached Appendix includes marked-up copies of each rewritten claim (37 C.F.R. §1.121(c)(1)(ii)).